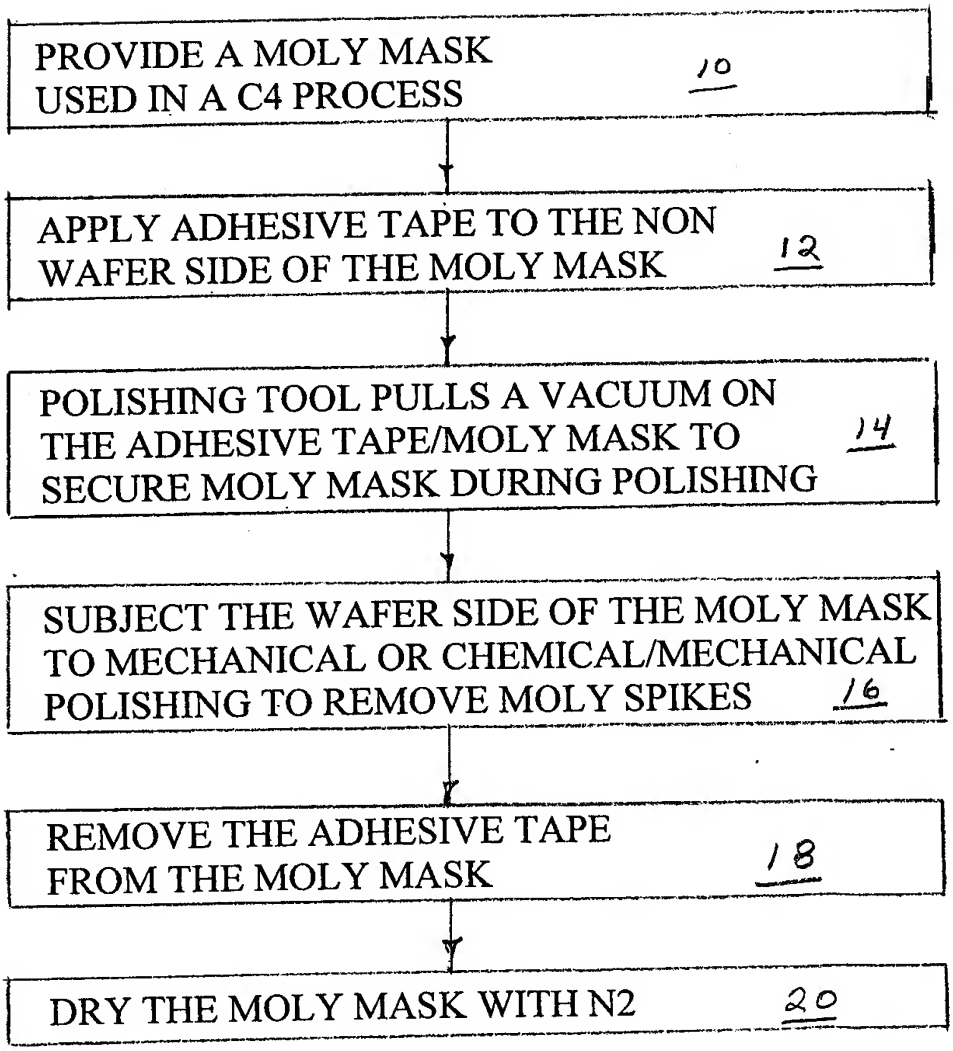
PROVIDE A MOLY MASK USED IN A C4 PROCESS
10
APPLY ADHESIVE TAPE TO THE NON WAFER SIDE OF THE MOLY MASK
12
POLISHING TOOL PULLS A VACUUM ON THE ADHESIVE TAPE/MOLY MASK TO SECURE MOLY MASK DURING POLISHING
14
SUBJECT THE WAFER SIDE OF THE MOLY MASK TO MECHANICAL OR CHEMICAL/MECHANICAL POLISHING TO REMOVE MOLY SPIKES
16
REMOVE THE ADHESIVE TAPE FROM THE MOLY MASK
18
DRY THE MOLY MASK WITH N2
20

FIGURE 1